



S/N 09/945,536

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar et al.

Serial No.: 09/945,536

Filed: August 30, 2001

Title: THERMAL PROCESSING OF METAL ALLOYS FOR AN IMPROVED CMP
PROCESS IN INTEGRATED CIRCUIT FABRICATION

Examiner: Caridad Everhart

Group Art Unit: 2825

Docket: 303.469US3

PATENT

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on September 5, 2002. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 18 and 20. The specific amendments to individual claims are detailed in the following marked up set of claims.

18. (Amended) A memory device comprising:
- an array of memory cells;
 - internal circuitry; and
 - metal contacts and interconnects coupled to the memory array and internal circuitry, wherein the metal contacts and interconnects are formed by annealing the memory at a temperature sufficient to drive alloy dopants into solid solution and quenching the memory prior to polishing the memory device to remove portions of a metal layer and form the metal contacts and interconnects.
20. (Amended) memory device comprising:
- an array of memory cells;
 - internal circuitry; and
 - metal contacts and interconnects coupled to the memory cells and internal circuitry,